

Hyper SuperServer SYS-112H-TN

1U UP Hyper with 8 hot-swap 2.5" NVMe/SAS/SATA bays and 2 PCIe 5.0 + 1 PCIe 5.0 AIOM slots

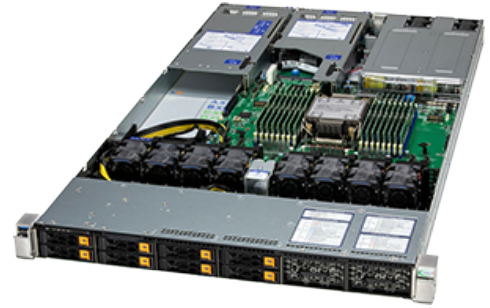


Key Applications

Virtualization, Financial, Scale Out All-Flash NVMe Storage, Data Center Enterprise Applications, Cloud Computing, AI Inference, CDN/vCDN/Cloud CDN,

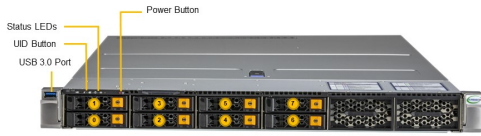
Key Features

- Hyper is a flagship performance rackmount server optimized for scale-out cloud workloads.;
- Single Intel® Xeon® 6 Processor.;
- 16 DIMM slots supporting up to 2TB of memory (6700E series CPU).;
- Double width add-on card support.;
- Flexible networking options with 1 AIOM networking slot (OCP NIC 3.0 compatible).;
- Breeze through high throughput workloads with PCIe 5.0 NVMe drive support.;
- Trusted Platform Module (TPM) 2.0 onboard.;
- Modularized and Tool-less design for easy serviceability.;



Form Factor	1U Rackmount Enclosure: 437 x 43 x 778.7mm (17.2" x 1.7" x 30.66") Package: 672 x 224 x 1100mm (26.46" x 8.82" x 43.31")
Processor	Single Socket E2 (LGA-4710) Intel® Xeon® 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache
GPU	Max GPU Count: Up to 1 double-width or 2 single-width GPUs Supported GPU: NVIDIA PCIe: L40S CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect
System Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 2TB 5200MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 8 bays <ul style="list-style-type: none"> • 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays Option A: Total 12 bays <ul style="list-style-type: none"> • 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bays • 4 front hot-swap 2.5" SAS*/SATA* drive bays (*NVMe/SAS/SATA support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 2 M.2 NVMe slots (M-key 2280/22110/25110; VROC required for RAID)
Expansion Slots	Default <ul style="list-style-type: none"> • 1 PCIe 5.0 x16 FHHL slot • 1 PCIe 5.0 x16 FHFL double-width slot • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	NVMe: NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required) Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 ports(rear) 1 USB 3.0 port(front) Video: 1 VGA port

(Front View – System)



Drive Bay	Description
0-7	8 Hot-swap 2.5" NVMe/SAS/SATA Drive Bays + up to 4 Optional Drive Bays*

*Requires additional parts in optional parts list

(Rear View – System)



Redundant Titanium Level Power Supplies

Slot	Slot Description
1	PCIe 5.0 x16 FH, 6.0L
2	PCIe 5.0 x16 Slot FH, 10.5" L
3	Not available with Intel® 6700E CPU configurations
4	ACM Slot (OCP 3.0)

System Cooling	Fans: 8 counter-rotating 40x40x56mm Fan(s) Air Shroud: 1 CPU Air Shroud
Power Supply	2x 1200W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 64MB SPI Flash
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 41.4 lbs (18.8 kg) Net Weight: 19.2 lbs (8.7 kg) Available Color: Silver
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X14SBH
Chassis	CSE-HS101-R000NFP